3D Metrology

Purpose	**True 3D Measurement Solutions for various process points such as Wafer Bumping, Post Dicing, Assembly & Post Test**
Technology	1. **OTF Triangulation 3D** – Designed for high volume, high speed 3D Metrology solutions for Post Dicing, Assembly & Post Test requirements. 2. **True Mold Thickness** – Patented Solution to measure 360 degree 3D topology measurement at production speed for packages used in portable mobility devices 3. **OTF Confocal 3D** – Designed for high volume, high speed 3D metrology solutions for Wafer Bumping & Post Dicing requirements 4. **Color Confocal 3D** – Designed for ultra high resolution 3D metrology for Critical Dimensional profiling measurements solutions for RDL, TSV or TTV of transparent surface layer

STI Products	OTF Triangulation	OTF Confocal	True Mold Thickness	Color Confocal
iFocus – Wafer 2D & 3D Scan	✓	✓		✓
Hexa – Tray 2D & 3D Scan	✓		✓	